ABSOLUTE MAXIMUM RATINGS¹ (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS
Vcc	Supply Voltage, Pins 4 & 6	V	3.6
Icc	Circuit Current	mA	15
PD	Power Dissipation ²	mW	270
Тор	Operating Temperature	°C	-40 to +85
Tstg	Storage Temperature	°C	-55 to +150
Pin	Input Power	dBm	+5

RECOMMENDED OPERATING CONDITIONS

	SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
	Vcc	Supply Voltage	V	2.7	3.0	3.3
•	Та	Operating Ambient Temperature	°C	-40	+25	+85

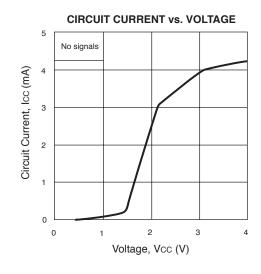
Notes:

- Operation in excess of any one of these parameters may result in permanent damage.
- 2. Mounted on a 50 x 50 x 1.6 mm epoxy glass PWB ($T_A = +85^{\circ}C$).

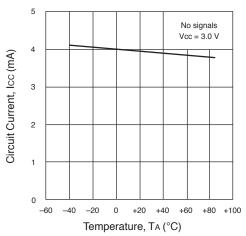
PIN FUNCTIONS

Pin No.	Symbol	Pin Voltage	Description	Internal Equivalent Circuit	
1	INPUT	1.09 V	Signal Input Pin. A internal matching circuit, configured with resistors, enable 50 W connection over a wide band. This pin must be coupled to signal source with capacitor for DC cut.	6	
2 3 5	GND	through external inductor	Ground pin. This pin should be connected to the system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All the ground pins must be connected together with wide ground pattern to decrease impedance difference.	4	
4	OUTPUT	Same as Vcc voltage	Signal output pin. This pin is designed as collector output. Due to the high impedance output, this pin should be externally equipped with matching LC matching circuit to next stage. For L, a size 1005 chip inductor can be chosen.	3 1 5	
6	Vcc	2.4 to 3.3	Power supply pin. This pin should be externally equipped with bypass capacitor to minimize its impedance.		

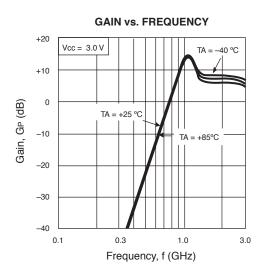
TYPICAL PERFORMANCE CURVES (Unless otherwise specified, TA = 25°C)

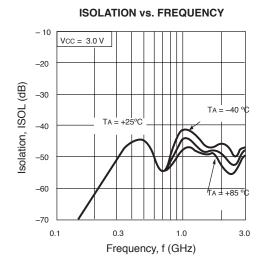


CIRCUIT CURRENT vs. TEMPERATURE

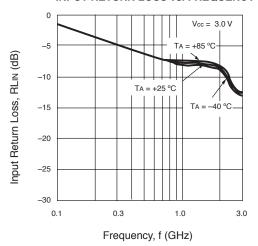


1.0 GHz Output Port Matching

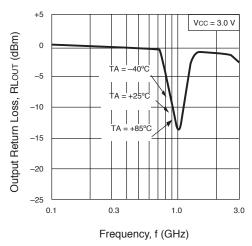




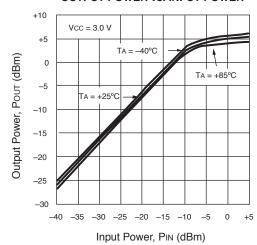
INPUT RETURN LOSS vs. FREQUENCY



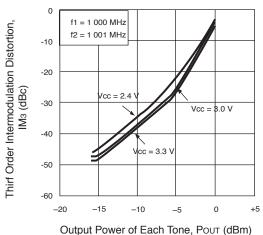




OUTPUT POWER vs. INPUT POWER

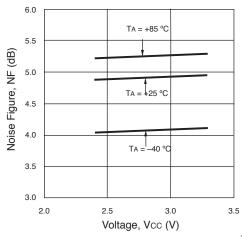


THIRD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE



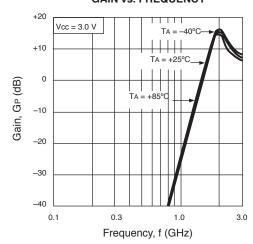
1.0 GHz Output Port Matching

NOISE FIGURE vs. VOLTAGE

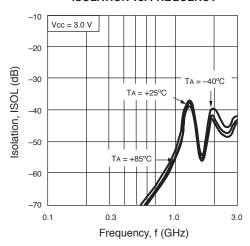


1.9 GHz Output Port Matching

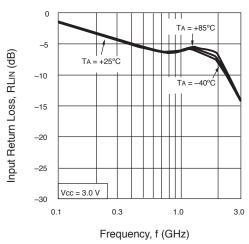
GAIN vs. FREQUENCY



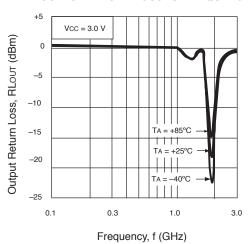
ISOLATION vs. FREQUENCY



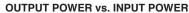
INPUT RETURN LOSS vs. FREQUENCY

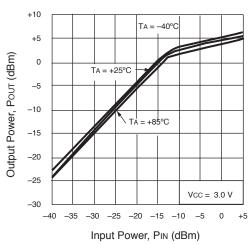


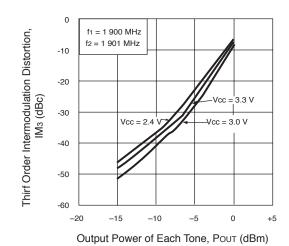
OUTPUT RETURN LOSS vs. FREQUENCY



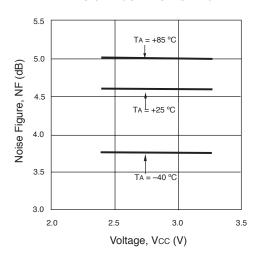
1.9 GHz Output Port Matching





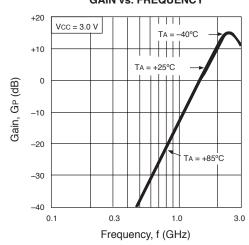


NOISE FIGURE vs. VOLTAGE

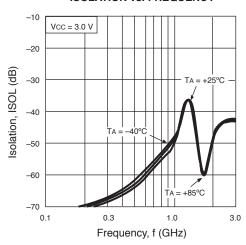


2.4 GHz Output Port Matching

GAIN vs. FREQUENCY

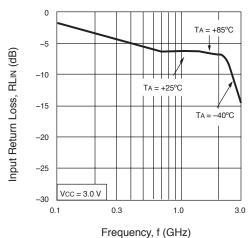


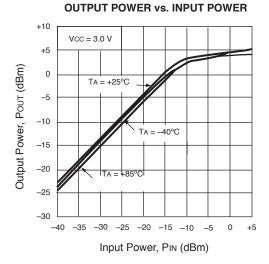
ISOLATION vs. FREQUENCY



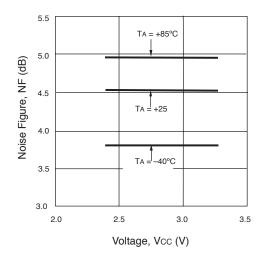
2.4 GHz Output Port Matching



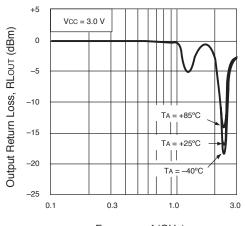




NOISE FIGURE vs. VOLTAGE

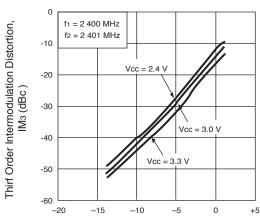


OUTPUT RETURN LOSS vs. FREQUENCY



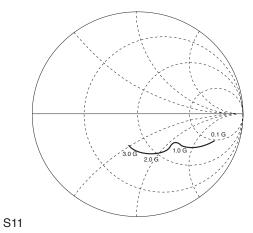
Frequency, f (GHz)

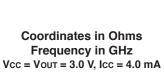
THIRD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE

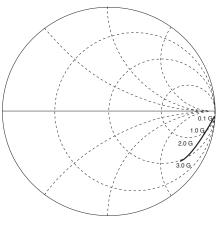


Output Power of Each Tone, POUT (dBm)

TYPICAL SCATTERING PARAMETERS (TA = 25°C)







S22

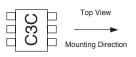
Vcc = Vout = 3.0 V, Icc = 4.0 mA =

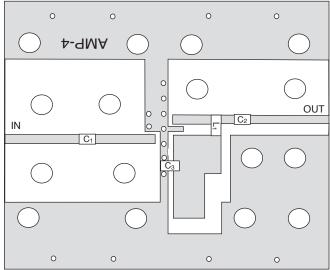
MAG	ANG
0.000	
0.996	-2.4
0.986	-4.0
0.980	-5.8
0.965	-7.5
0.958	-8.6
0.950	-10.1
0.941	-11.2
0.935	-12.4
0.929	-13.8
0.918	-14.9
0.914	-16.0
0.903	-17.0
0.895	-18.3
0.891	-19.5
0.884	-20.4
0.877	-21.1
0.867	-22.1
0.877	-21.1
0.859	-24.4
0.852	-25.1
0.846	-25.9
0.847	-26.4
0.839	-27.4
0.839	-28.2
0.838	-29.1
0.834	-29.7
0.830	-30.6
0.831	-31.4
0.837	-32.0
0.831	-33.4
0.833	-34.0
	0.980 0.965 0.958 0.950 0.941 0.935 0.929 0.918 0.914 0.903 0.895 0.891 0.884 0.877 0.867 0.877 0.859 0.852 0.846 0.847 0.839 0.839 0.839 0.838 0.839 0.831

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

COMPONENT LIST

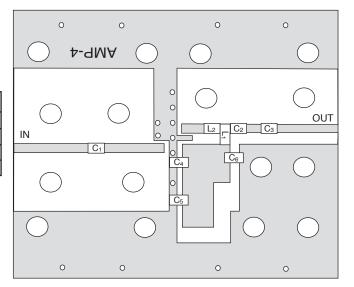
	1.0 GHz Output Port Matching		
C ₁	1000 pF		
C2	0.75 pF		
Сз	10 pF		
L ₁	12 nH		





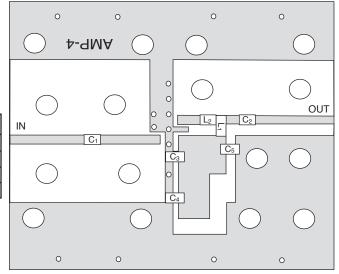
COMPONENT LIST

	1.9GHz Output Port Matching	
C1, C3, C5, C6	1000 pF	
C2	0.75 pF	
C4	10 pF	
L1	3.3 nH	



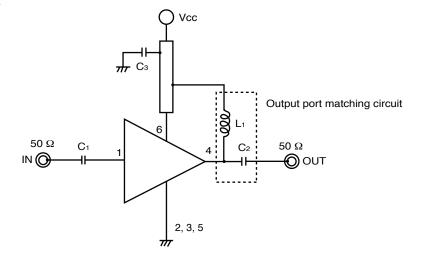
COMPONENT LIST

	2.4 GHz Output Port Matching	
C1, C2, C4, C5	1000 pF	
Сз	10 pF	
L1	1.8 nH	
L2	2.7 nH	

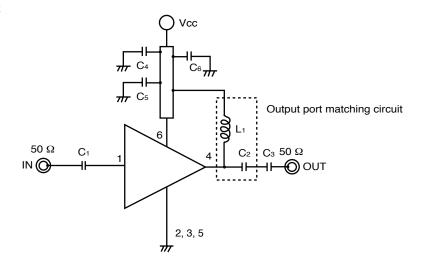


TEST CIRCUITS

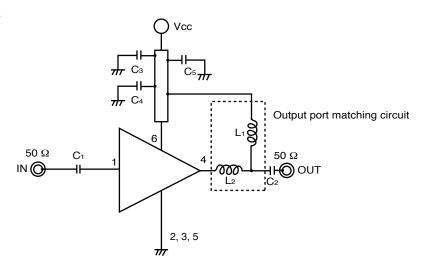
<1> f = 1.0 GHz



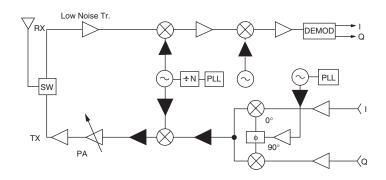
<2> f = 1.9 GHz



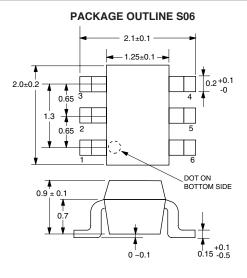
<3> f = 2.4 GHz



SYSTEM APPLICATION EXAMPLE



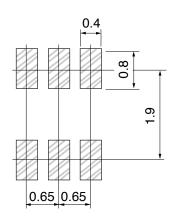
OUTLINE DIMENSIONS (Units in mm)



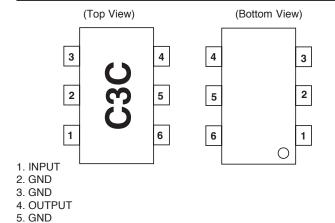
RECOMMENDED P.C.B. LAYOUT (Units in mm)

Note:

All dimensions are typical unless otherwise specified.



LEAD CONNECTIONS



ORDERING INFORMATION

PART NUMBER	QTY
UPC8179TB-E3-A	3K/Reel

Note:

6. Vcc

Embossed tape, 8 mm wide. Pins 1, 2, 3 are in tape pull-out direction.

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.



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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A -AZ Not Detected (*)		
Mercury	< 1000 PPM	Not Detected		
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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